

# **Intel<sup>®</sup> Server Board SE7505VB2 Memory List Test Report Summary**



*Revision 42.0  
January 2006*

<b>Revision History</b>		
<b>Date</b>	<b>Rev</b>	<b>Modifications</b>
1/03	.5	Initial Release.
Jan/03	1.0	Added Dataram* 256MB parts. Added Infineon* 128MB, 256MB and 512MB parts. Added Samsung* 256MB and 512MB parts. Added Aved* and Viking* 512MB parts. (In shaded area)
Feb/03	2.0	Added ATP*, Aved, MSC* and Dataram 1GB parts. Added ATP, Avant*, Buffalo*, Dataram, MSC, Ventura* and Viking 512MB parts. Added ATP and Viking 256MB parts. (In shaded area)
Mar/03	3.0	Added Micron* 256MB, 512MB and 1GB parts. Added, Buffalo, Centon* 256MB and 512MB parts. Added Samsung 512MB, 256MB and 1GB parts. Added Infineon 1GB and 2GB parts. Added ATP 256MB part. (In shaded area)
Mar/03	4.0	Added ATP 256MB parts. Added Viking 512MB parts. Added Avant and Centon 1GB parts. Added ATP 2GB parts. (In shaded area)
April/03	5.0	Added Dataram 256MB parts. Added Avant and ATP 512MB parts. Added Avant, ATP and Viking 1GB parts.
May/03	6.0	Added ATP 128MB. Added ATP, Centon and Buffalo 256MB parts. Added Smart, Viking, Avant and MSC parts. Added Infineon, Avant and Smart* 1GB parts. Added Viking 2GB parts. (In Shaded area)
June/03	7.0	Added ATP 128MB parts. Added Viking 256MB parts. Added Avant, Buffalo and Viking 512MB parts. Added Dataram 1GB parts. (In shaded area)
June/03	8.0	Added Buffalo and Avant 1GB parts. Added Smart 2GB parts. Added Samsung 128MB, 256MB and 512MB parts. Added Micron 512MB part. (In shaded area)
July/03	9.0	Added TRS and Itaucom* 256MB parts. Added TRS* and Legend* 512MB parts. Added Legend 1GB parts. Added Samsung 256MB and 1GB parts. (In shaded area)
July/03	10.0	Added Smart, Ventura and Itaucom 512MB parts. Added Itaucom and Smart 1GB parts. Added Samsung 128MB and 1GB parts. (In shaded area)
Aug/03	11.0	Added Smart and Samsung 512MB parts. Added TRS and Viking 1GB parts. (In shaded area). Also Updated EOL status.
Sept/03	12.0	Added Avant 512MB parts. Added Centon 1GB parts. Added TRS 2GB parts. Added Kingston* 256MB and 512MB parts. (In shaded area)
Oct/03	13.0	Added Centon and Ventura 512MB parts. Added Ventura 1GB parts. (In shaded area). Also updated EOL status
Nov/03	14.0	Added Kingston 128MB part. Added Legend and ATP 512MB parts. Added Micron, Legend and Avant 1GB parts. Added Infineon 256MB and 1GB parts. Added Avant 2GB parts. Correction made for Micron 256MB and 512MB parts. (In shaded area)
Nov/03	15.0	Added Legend 256MB and 512MB parts. Added ATP, Avant, Smart, and Wintec* 1GB parts. Added Dataram 2GB parts. (In shaded area)
Nov/03	16.0	Added ATP 1GB parts. Added Smart 256MB and 2GB parts. (In shaded area)
Dec/03	17.0	Added Smart and Legacy 512MB parts. Added Legend and Legacy* 1GB parts. (In shaded area)
Jan/04	18.0	Added Smart 1GB parts. Added Legacy 2GB parts. (In shaded area)
Feb/04	19.0	Added Avant 512MB and 1GB parts. Added Centon 1GB parts. (In shaded area). Also updated EOL status.
Feb/04	20.0	Added Dane-Elec* 256MB parts. Added Avant 512MB parts. Added Buffalo, Smart and TRS 1GB parts. New CMTL address. (In shaded area)
Mar/04	21.0	Added Ventura 512MB parts. Added Dataram 1GB parts. (In shaded area) Also Updated EOL status
Apr/04	22.0	Added Legacy 512MB, 1GB and 2GB parts. Added Ventura 1GB and 2GB parts. (In shaded area)
May/04	23.0	Added ATP 256MB parts. Legacy, Smart, and Avant 1GB parts.
Jun/04	24.0	Added Ventura 512MB and 1GB parts. Added ATP 1GB parts. (In shaded area)
Jun/04	25.0	Added Kingston 1GB parts. (In shaded area)

<b>Revision History</b>		
<b>Date</b>	<b>Rev</b>	<b>Modifications</b>
Aug/04	26.0	Added Viking 256MB, 512MB and 1GB parts. Added Dataram 1GB parts. Added Kinston 2GB parts. (In shaded area)
Sept/04	27.0	Added support for DDR333 modules. Added Legend, TRS, Avant 512MB parts. Added Wintec and Smart 1GB parts. (In shaded area)
Sep/04	28.0	Added Buffalo 512MB and 1GB parts. (In shaded area)
Sep/04	29.0	Added Smart 1GB parts. (In shaded area)
Oct/04	30.0	Added Viking 1GB parts. (In shaded area)
Nov/04	31.0	Added Infineon and Samsung 256MB parts. Added Buffalo and Infineon 512MB parts. Added TRS, Avant, Micron and Samsung 1GB parts. (In shaded area)
Dec/04	32.0	Added Avant 1GB parts. (In shaded area)
Dec/04	33.0	Added Buffalo 1GB parts. (In shaded area)
Mar/05	34.0	Added note on Lead free modules (these modules are now in bold text). Added Legend 256MB parts. Added Kingston 1GB parts. (In shaded area)
Apr/05	35.0	Added Avant 1GB parts and Legend 2GB parts. (In shaded area)
Apr/05	36.0	Added Avant 512MB and Kingston 2GB parts. (In shaded area)
May/05	37.0	Updated Contact information. Updated Kingston part number from KVR266X72RC25/512 to KVR266S4R25/512i per vendor's request. (In shaded area)
Jun/05	38.0	Added Avant 512MB parts. (In shaded area)
Jun/05	39.0	Added Kingston 512MB and 1GB parts. Added Avant 1GB parts. (In shaded area)
Aug/05	40.0	Added Kingston 512MB and 1GB parts. Added TRS 2GB parts. (In shaded area)
Oct/05	41.0	Added Kingston 2GB part. (In shaded area)
Jan/06	42.0	Added Legend 512MB, 1GB and 2GB parts. (In shaded area)

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The Intel® Server Board SE7505VB2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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## Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7505VB2. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)<sup>1</sup>. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel's Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft\* Windows\* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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<sup>1</sup> CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690  
Fax (949) 716-8691

Computer Memory Test Lab (CMTL)  
24 Hammond Suite F  
Irvine, CA 92618  
<http://www.cmtlabs.com/>

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## Qualified Memory for the Intel® Server Board SE7505VB2

The Intel® SE7505VB2 server board has 4 DIMM sockets supporting up to 8 GB of Registered ECC DDR266 or DDR333 memory using four 72-bit DIMM modules. These four DIMM sockets constitute two memory banks; Bank1 with contiguous sockets labeled DIMM1A and DIMM1B, and Bank2 with contiguous sockets labeled DIMM2A and DIMM2B<sup>2</sup>. When memory is installed in pairs, DIMM Bank1 must be populated before DIMM Bank2. Memory within a DIMM bank must be identical. For customers requiring a lower cost configuration, a single DIMM may be populated in the DIMM1A socket. If this is done, the Intel® x4 Single Device Data Correction (Intel x4 SDDC) technology and memory interleaving will not be enabled. DIMM and memory configurations must adhere to the following:

- DDR266 and DDR333 registered ECC 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMM organization: x72 ECC
- Pin Count: 184
- Memory capacity: 128MB, 256MB, 512MB, 1GB and 2GB
- Serial PD: JEDEC Rev 2.0
- Interface: SSTL2
- CAS Latency: 2 and 2.5
- Minimum configuration: 256MB using two 128MB DIMMs in Bank1 for full memory functionality or 128MB using a single 128MB DIMM in socket DIMM1A with a reduced memory feature set.
- One or two memory banks may be populated.

**Note:**

- Memory qualification is done by testing identical memory modules in all DIMM sockets. Memory qualification does not include testing of mixed DIMM type and/or vendors; mixing of DIMM type and/or vendors is not recommended.
- Some modules on this list may contain “stacked” DRAM parts. Stacked (low profile) 1GB DIMMs and all 2GB DIMM parts require a special memory cooling duct be installed on the SE7505VB2 server board. Please consult the Intel Server Board SE7505VB2 Technical Product Specification for details on obtaining and using this duct

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Below is a chart that lists the current supported memory types:

DDR266 Registered SDRAM Module Configurations for Cas Latency 2 & 2.5					
DIMM Capacity	DIMM Organization	DRAM Density	DRAM Organization	# DRAM Devices/rows/Banks	# Address bits rows/Banks/column
128MB	16M x 72	64Mbit	16M x 4	18/1/4	12/2/10
128MB	16M x 72	64Mbit	8M x 8	18/2/4	12/2/9
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	64Mbit	16M x 4	36/2/4	12/2/10
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	128Mbit	32M x 4	36/2/4	12/2/11
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12
DDR333 Registered DRAM Module Configuration Matrix					
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11

The memory controller in the server board SE7505VB2 supports memory scrubbing, single-bit error correction, multiple-bit error detection and the Intel® x4 Single Device Data Correction (SDDC) support with x4 DIMMs only. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs. The Intel® x4 Single Device Data Correction gives the memory sub-system the ability to withstand a multi-bit failure within a DRAM device, including a failure that causes incorrect data on all data bits of the device.

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7505VB2. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system



operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

For a full description of the SE7505VB2 server board memory features refer to the *Intel® Server Board SE7505VB2 Technical Product Specification* available on-line at

<http://support.intel.com/support/motherboards/server/SE7505VB2>

**Caution:** Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

**Note:** This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

***This list is subject to change without notice.***

## *Server Board SE7505VB2*

### *Registered, ECC, DDR266 DIMM Modules 128MB Sizes (16Mx72)*

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>EOL</b>
Samsung*	M312L1713DT0-CA2	K4H280838D-TCA2	Samsung		12/18/02	2	Yes	(16Mx8) <sup>*</sup> <sub>9</sub>	
Infineon*	HYS72D16500GR-7-A	HYB25D128800AT-7	Infineon		1/27/03	2	Yes	(16Mx8) <sup>*</sup> <sub>9</sub>	
+ATP Electronics*	AB16L72A8SEB0S	K4H280838D-TCB0 rev D	Samsung	SB184A08 L rev 1	4/14/03	2.5		(16Mx8) <sup>*</sup> <sub>9</sub>	EOL
+ATP Electronics	AB16L72Q8SEB0S	K4H280838E-TCB0 rev E	Samsung	SB184Q08 L1 rev 1	5/7/03	2.5	Yes	(16Mx8) <sup>*</sup> <sub>9</sub>	EOL
Samsung	M383L1713ETS-CB0	K4H280838E-TCB0	Samsung		4/22/03	2.5		(16Mx8) <sup>*</sup> <sub>9</sub>	
Samsung	M312L1713ETS-CA2	K4H280838E-TCA	Samsung		7/25/03	2	Yes	(16Mx8) <sup>*</sup> <sub>9</sub>	
Kingston*	KVR266X72RC25/128	HY5DU28822BT-H	Hynix		10/10/03				

*Modules shaded in blue are low profile.*

**Modules in bold text do not contain Lead.**

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal and physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

## Server Board SE7505VB2

### Registered, ECC, DDR266 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Infineon	HYS72D32001GR-7-A	HYB25D128400AT-7A	Infineon		1/12/03	2		(32Mx4) *18	
+Dataram*	DTM63640A	HYB25D128400AT-7 rev A	Infineon	40581A rev A	1/23/03	2.5	Yes	(32Mx4) *18	EOL
Samsung	M383L3310ETS-CB0	K4H280438E-TCB0	Samsung		1/23/03	2.5		(16Mx8) *18	
+ATP Electronics	AB32L72R4S4B0S	K4H280438C-TCB0 rev C	Samsung	SB184R04 L1	1/30/03	2.5	Yes	(32Mx4) *18	EOL
+ATP Electronics	AB32L72Q8SQB0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08 L1	2/10/03	2.5	Yes	(32Mx8) *9	EOL
+Viking*	VI4CR327228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000905A	1/30/03	2.5	Yes	(32Mx8) *9	EOL
+Viking	VI4CR327224CTHL1	K4H280438D-TCB0 rev D	Samsung	03-0291 Rev A	2/24/03	2.5	Yes	(32Mx4) *18	EOL
+Buffalo*	DD266-R256/SD	K4H280838D-TCB0 rev D	Samsung	RCE0501-AB	3/3/03	2.5		(16Mx8) *18	
+Centon Electronics*	TOP02-D004D	MT46V32M4TG-75 rev B	Micron	LE36DDT1 844R rev A	3/6/03	2.5	Yes	(32Mx4) *18	EOL
Micron*	MT9VDDT3272G-265C3	MT46V32M8-75 C	Micron		3/3/03	2.5	Yes	(32Mx8) *9	EOL
Samsung	^M312L3223DT0-CAA	K4H560838D-TCAA	Samsung		3/12/03	2	Yes	(32Mx8) *9	
+ATP Electronics	AB32L72A8S4B0	NT5DS16M8AT-7K rev D	Nanya	SB184A08 L rev1	3/17/03	2.5		(16Mx8) *9	EOL
+Dataram	DTM63640B	MT46V32M4TG-75 rev B	Micron	40581A rev A	4/4/03	2.5	Yes	(32Mx4) *18	
+Centon Electronics	TOP02-D007G	MT46V32M4TG-75 rev B	Micron	LE36DDT1 844R rev A	4/21/03	2.5	Yes	(32Mx4) *18	EOL
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/21/03	2.5	Yes	(32Mx8) *9	
+Buffalo	DD266-R256/SE	K4H280838E-TCB0 rev E	Samsung	RCE0502-AA	4/24/03	2.5		(16Mx8) *9	
+ATP Electronics	AB32L72A8S4B0S	K4H280838D-TCB0 rev D	Samsung	SB184A08 L rev1	4/24/03	2.5		(16Mx8) *9	EOL
+Viking	VI4CR327228DTHL3	MT46V32M8TG-75 rev C	Micron	0000905A	4/30/03	2.5	Yes	(32Mx8) *9	

**Registered, ECC, DDR266 DIMM Modules  
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L3310DT0-CA2	K4H280438D-TCA2	Samsung		6/11/03	2	Yes	(32Mx4) *18	
+TRS*	TRS21150	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/16/03	2	Yes	(32Mx8) *9	
ITAUCOM*	256E2665R28	ICM4L560807-65	Micron	0247 A	6/23/03	2.5	Yes	(32Mx8) *9	
Samsung	M312L3223ETS-CA2	K4H560838E-TCCA2	Samsung		6/23/03	2	Yes	(32Mx8) *9	
Kingston	KVR266X72RC25/256	MT46V32M8-75C	Micron		9/8/03	2.5	Yes	(32Mx8) *9	
+Legend*	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U081 8-A rev 1	10/27/03	2.5	Yes	(32Mx8) *9	
+Smart Modular Technologies*	SM3272RDDR320LP-I	HYB25D256800BT-7 rev B	Infineon	184-L13-2	11/10/03	2	Yes	(32Mx8) *9	
+Dane-Elec*	ODLD266R072325I-1MC	MT46V32M8TG-6T rev C	Micron	DR1G872-A rev A	2/3/04	2.5	Yes	(32Mx8) *9	
+ATP Electronics	AB32L72Q8SQB0S	K4H560838F-TCB3 rev F	Samsung	SB184Q08 L1	4/29/04	2.5	Yes	(32Mx8) *9	
+Viking	VI4CR327228DTHL4	MT46V32M8TG(P)-6T rev G	Micron	0000985A	7/2/04	2.5	Yes	(32Mx8) *9	
Samsung	M312L3223ETS-CAA	K4H560838E-TCAA	Samsung		11/2/04	2	Yes	(32Mx8) *9	
Infineon	HYS72D32300GBR-7-B	HYB25D256800BC-7	Infineon		11/2/04	2	Yes	(32Mx8) *9	
Infineon	HYS72D32300GBR-7F-B	HYB25D256800BC-7F	Infineon		11/2/04	2	Yes	(32Mx8) *9	

**Registered, ECC, DDR333 DIMM Modules  
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L3272YC6-RU1HDC5B	HY5DU56822BT-D43 rev B	Hyundai	DRR1U081 8-A rev 1	3/11/05	2.5	Yes	(32Mx8) *9	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal and physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

## Server Board SE7505VB2

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Infineon	HYS72D64320GBR-7-B	HYB25D256800BC-7	Infineon		12/16/02	2	Yes	(32Mx8) *18	
Infineon	HYS72D64000GR-7-B	HYB25D256400BT-7	Infineon		1/14/03	2		(64Mx4) *18	
Samsung	M312L6420DT0-CA2	K4H560438D-TCA2	Samsung		1/16/03	2	Yes	(64Mx4) *18	
Samsung	M383L6420DTS-CA2	K4H560438D-TCA2	Samsung		1/19/03	2		(64Mx4) *18	
+Aved Memory Products*	AMP383D6420CT3-CB0/S	K4H560438C-TCB0 rev C	Samsung	105611 rev A	1/23/03	2.5	Yes	(64Mx4) *18	EOL
+Viking	VI4CR647228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000905A G	1/23/03	2.5	Yes	(32Mx8) *18	EOL
+Buffalo	DD266-R512/SD	K4H560838D-TCB0 rev D	Samsung	RCE0501-AB	2/11/03	2.5		(32Mx8) *18	
+Dataram	DTM63641G	MT46V64M4TG-75 rev C	Micron	40581A rev A	2/17/03	2.5	Yes	(64Mx4) *18	
Ventura Technology Group*	D52WPK31SV	K4H560438D-TCB0 rev D	Samsung	V218	2/13/03	2.5	Yes	(64Mx4) *18	EOL
+ATP Electronics	AB64L72R4S8B0S	K4H560438D-TCB0 rev D	Samsung	SB184R04 L1	2/11/03	2.5	Yes	(64Mx4) *18	EOL
+ATP Electronics	AB64L72Q8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08 L1 rev 1	2/6/03	2.5	Yes	(32Mx8) *18	EOL
+Viking	VI4CR647224DTHL1	K4H560438D-TCB0 rev D	Samsung	03-0291 rev A	2/3/03	2.5	Yes	(64Mx4) *18	EOL
+Avant Technology*	AVM7264R39C2266K 1-A	NT5DS32M8AT-7K rev A	Nanya	50-1411-01-A rev A	1/30/03	2	Yes	(32Mx8) *18	EOL
+Dataram	DTM63641E	HYB25D256400BT-7 rev B	Infineon	40581A rev A	2/6/03	2.5	Yes	(64Mx4) *18	EOL
+MSC Vertriebs GmbH*	MSC 512M00098	MT46V32M8TG-75 rev B	Micron	PCB M0481LA2	2/13/03	2.5		(32Mx8) *18	EOL
+ATP Electronics	AB64L72A8S8B0	NT5DS32M8AT rev D	Nanya	SB184A08 L rev1	3/3/03	2.5		(32Mx8) *18	EOL
Micron	MT18VDDT6472G-265B1	MT46V64M4-75 B	Micron		3/5/03	2.5		(64Mx4) *18	
Samsung	^M383L6420DTS-CAA	K4H560438D-TCAA	Samsung		3/5/03	2		(64Mx4) *18	
+Centon Electronics	TOP02-D005E	MT46V64M4TG-75 rev B	Micron	LE36DDT1 844R rev A	3/6/03	2.5	Yes	(64Mx4) *18	EOL
+Buffalo	DD266-R512/MB	46V32M8-75 rev B	Micron	RCE0501-AB	3/10/03	2.5		(32Mx8) *18	
Micron	MT18VDDT6472G-265C3	MT46V64M4-75 C	Micron		3/10/03	2.5	Yes	(64Mx4) *18	EOL
+Viking	VI4CR647228DTHL2	K4H560838D-TCB0	Samsung	0000905A	3/12/03	2.5	Yes	(32Mx8) *18	EOL

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Avant Technology	AVM7264R38C5266K0-A	MT46V64M4TG-75 B rev B	Micron	50-1415-01 rev B	3/24/03	2.5	Yes	(64Mx4)*18	EOL
+ATP Electronics	AB64L72A8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184A08 L rev1	3/24/03	2.5		(32Mx8)*18	EOL
+Smart Modular Technologies	SM6472RDDR3H1LP-N	NT5DS64M4AT-7K	Nanya	P52G184N ESZ6G001 rev A	4/11/03	2.5	Yes	(64Mx4)*18	
+Viking	VI4CR647224DTHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	4/17/03	2.5	Yes	(64Mx4)*18	EOL
+Avant Technology	AVM7264R39C5266K1-A	MT46V32M8-75 B rev B	Micron	50-1411-01-A rev A	4/21/03	2.5	Yes	(32Mx8)*18	EOL
+Avant Technology	AVM7264R38C2266K0-A	NT5DS64M4AT-7K rev A	Nanya	50-1415-01 rev B	4/9/03	2	Yes	(64Mx4)*18	EOL
+MSC Vertriebs GmbH	MSC 512M00094	HYB25D256800BT-7 rev B	Infineon	PCB M0481LA2	4/9/03	2		(32Mx8)*18	EOL
+Avant Technology	AVM7264R38C5266K0-A	MT46V64M4TG-75 C rev C	Micron	50-1415-01-B rev B	5/2/03	2.5	Yes	(64Mx4)*18	EOL
+Avant Technology	AVM7264R39C5266K1-A	MT46V32M8TG-75 C rev C	Micron	50-1411-01-A rev A	5/7/03	2.5	Yes	(32Mx8)*18	EOL
+Buffalo	DD266L-R512/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/30/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CR647228DTHL3	MT46V32M8TG-75 rev B	Micron	0000905A	5/2/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CR647228DTHL4	MT46V32M8TG-75 rev C	Micron	0000905A rev A	5/2/03	2.5	Yes	(32Mx8)*18	
Samsung	M312L6420DT0-CB0	K4H560438D-TCB0	Samsung		04/22/03	2.5	Yes	(64Mx4)*18	
Samsung	M383L6420DTS-CB0	K4H560438D-TCB0	Samsung		04/22/03	2.5		(64Mx4)*18	
Samsung	M383L6420ETS-CB0	K4H560438E-TCB0	Samsung		04/22/03	2.5		(64Mx4)*18	
+TRS	TRS21151	HYB25D256400BT-7 rev B	Infineon	M0530LA1 rev 1	6/18/03	2	Yes	(64Mx4)*18	
+Legend	L6472YC5-PPASDC5D	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	6/18/03	2.5	Yes	(64Mx4)*18	EOL
+Legend	L6472TC5-RR2HDC5A	HY5DU56822AT-H rev A	Hyundai	DRR720818A rev 2	6/23/03	2.5		(32Mx8)*18	EOL
+TRS	TRS21152	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/18/03	2	Yes	(32Mx8)*18	
Samsung	M312L6420ETS-CA2	K4H560438E-TCA2	Samsung		6/23/03	2	Yes	(32Mx8)*9	

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
ITAUCOM	512E2665R24	ICM4L560407-65	Micron	0269 A	6/30/03	2.5	Yes	(64Mx4)* 18	
+Smart Modular Technologies	SM6472RDDR320LP-I	HYB25D256400BT-7 rev B	Infineon	184-M12-2	7/15/03	2	Yes	(64Mx4)* 18	
+Ventura Technology Group	D52WPK31RV	NT5DS64M4BT-75 rev B	Nanya	V218	7/17/03	2.5	Yes	(64Mx4)* 18	
+Smart Modular Technologies	SM6472RDDR3H1LP	K4H560438D-TCB0 rev D	Samsung	M312L3310T0	7/24/03	2.5	Yes	(64Mx4)* 18	
Samsung	^M312L6420ETS-CAA	K4H560438E-TCAA	Samsung		8/5/03	2	Yes	(64Mx4)* 18	
+Avant Technology	AVM7264R38C5266K0-A	NT5DS64M4BT-75B rev B	Nanya	50-1415-01-B rev B	8/26/03	2.5	Yes	(64Mx4)* 18	
Kingston	KVR266S4R25/512i	HYB25D256400BT-7	Infineon		9/8/03	2.5	Yes	(64Mx4)* 18	
+Centon Electronics	TOP02-D019S	MT46V32M8TG-6 rev C	Micron	DR1G872-A	9/18/03	2.5	Yes	(32M x 8)* 18	
+Ventura Technology Group	D52WVK25SV	K4H560838E-TCB3 rev E	Samsung	V208	9/26/03	2.5	Yes	(32M x 8)* 18	
+Legend	L6472YC5-182HDD5A	HY5DU56422AT-K rev A	Hyundai	184RL rev 2	10/3/03	2.5	Yes	(64Mx4)* 18	
+ATP Electronics	AB64L72Q8S8B0S	K4H560838E-TCB3 rev E	Samsung	SB184Q08L1	9/30/03	2.5	Yes	(32M x 8)* 18	
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	10/27/03	2.5	Yes	(32M x 8)* 18	
+Smart Modular Technologies	SM6472RDDR325LP-S	K4H560438E-TCB0 rev E	Samsung	M312L3310ETS	12/10/03	2.5	Yes	(64Mx4)* 18	
+Legacy Electronics Inc.*	88L6JDLR-1LDG	LED64408TA-6	Legacy	LE36DDT1844R rev A	12/08/03	2.5	Yes	(64Mx4)* 18	
+Avant Technology	AVM7264R39C5266K1-A	MT46V32M8TG-75 rev G	Micron	50-1411-01-A rev A	1/23/04	2.5	Yes	(32M x 8)* 18	
+Ventura Technology Group	D52WVK25MV3	MT46V32M8TG-6T rev C	Micron	V208	3/11/04	2.5		(32M x 8)* 18	
+Legacy Electronics Inc.	88S6JDLR-1JDG	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	4/12/04	2	Yes	(64Mx4)* 18	
+Ventura Technology Group	D52WVK42SV	K4H560838E-TCB3 rev E	Samsung	DR1G872-A	5/26/04	2.5	Yes	(32M x 8)* 18	
+Viking	VI4CR647228DTHL5	MT46V32M8TG(P)-6T rev G	Micron	0000985A	7/8/04	2.5	Yes	(32M x 8)* 18	

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L6472YC5-PPASDD5D	K4H560438D-TCB3 rev D	Samsung	18-25141A Rev A	7/27/04	2.5	Yes	(64Mx4)* 18	
+TRS	TRS21202	HYB25D256400CE-7 rev C	Infineon	M0530LA1 rev 1	8/9/04	2	Yes	(64Mx4)* 18	
+Avant Technology	AVM7264R39C5266K1-MVA	V58C2256804SAT5 B rev A	Mosel Vitelic	50-1411-01-A rev A	7/28/04	2.5	Yes	(32Mx8)* 18	
Infineon	HYS72D64500GR-7-A	HYB25D256400AT-7	Infineon		11/2/04	2	Yes	(64Mx4)* 18	
+Avant Technology	AVM7264R39C5266K1-MTG	MT46V32M8TG-75 rev G	Micron	50-1411-01-A rev A	6/14/05	2.5	Yes	(32Mx8)* 18	

**Registered, ECC, DDR333 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333L-R512/MG	MT46V32M8TG(P)-6T rev G	Micron	1D188EF-AA	9/2/04	2.5	Yes	32Mx8)* 18	
+Buffalo	DD333L-R512/SF	K4H560838F-TCB3 rev F	Samsung	1D188EF-AA	11/11/04	2.5	Yes	32Mx8)* 18	
+Avant Technology	AVM7264R52C5333K1-MTD	MT46V64M8TG-6T rev D	Micron	50-1411-01-A rev A	4/6/05	2.5	Yes	(32Mx8)* 18	
+Kingston	KVR333S4R25/512I	HYB25D256400CC-6 rev C	Infineon	2025161-001.B00	6/27/05	2.5	Yes	(64Mx4)* 18	
+Kingston	KVR333S4R25/512I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na	7/20/05	2.5	Yes	(64Mx4)* 18	
+Legend	<b>L6472YC6-RU1HDHSC</b>	<b>HY5DU12822CTP-J rev C</b>	<b>Hynix</b>	<b>DDR1U0818 rev A</b>	<b>12/20/05</b>	<b>2.5</b>	<b>Yes</b>	<b>(64Mx8)* 9</b>	

Modules shaded in blue are low profile.

**Modules in bold text do not contain Lead.**

(^)**This is a 2-2-2 part.**

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal and physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.



## Server Board SE7505VB2

### Registered, ECC, DDR266 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L2828DT0-CA2	K4H560438D-TCA2	Samsung		12/26/02	2	Yes	(64Mx4)*36	
+MSC Vertriebs GmbH	MSC001G00096	HYB25D512800AT-7 rev A	Infineon	M0481LA2	2/19/03	2		(64M x 8)*18	EOL
+Dataram	DTM63653B	HYB25D256400BC-7 rev B	Infineon	40599A rev A	2/17/03	2.5	Yes	(64Mx4)*36	EOL
+Aved Memory Products	AMP383D2827DT1-CB0/S	K4H560438D-TCB0 rev D	Samsung	105605 rev A	2/7/03	2.5		(64Mx4)*36	EOL
+ATP Electronics	AB28L72T4SQB0S	K4H560438D-TCB0 rev D	Samsung	SB184T04L2 rev 2	2/19/03	2.5		(64Mx4)*36	EOL
+Dataram	DTM63653C	K4H560438D-GCA2 rev D	Samsung	40599A rev A	2/24/03	2.5	Yes	(64Mx4)*36	EOL
+ATP Electronics	AB28L72P4SMB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1	2/24/03	2.5	Yes	(64Mx4)*36	EOL
Infineon	HYS72D128500GR-7-A	HYB25D512400AT-7	Infineon		2/19/03	2	Yes	(128Mx4)*18	
Samsung	^M312L2828DT0-CAA	K4H510638D-TCAA	Samsung		3/5/03	2	Yes	(64Mx4)*36	
Micron	MT36VDDT12872G-265C2	MT46V64M4TG-75 rev C	Micron	0232 rev A	3/6/03	2.5	Yes	(64Mx4)*36	EOL
+Avant Technology	AVM7228R38C5266K3-A	MT46V64M4TG-75 B rev B	Micron	BRDB45A rev A	3/19/03	2.5		(64Mx4)*36	EOL
+Avant Technology	AVM7228R38C5266K3-A	MT46V64M4TG-75 C rev C	Micron	BRDB45A rev A	3/17/03	2.5		(64Mx4)*36	EOL
+Centon Electronics	TOP02-D006F	MT46V64M4TG-75C rev C	Micron	LE36DDT1844R rev A	3/19/03	2.5	Yes	(64Mx4)*36	EOL
+Avant Technology	AVM7228R38C5266K3-A	K4H560438D-TCB0 rev D	Samsung	BRDB45A rev A	3/31/03	2.5		(64Mx4)*36	EOL
+Viking	VI4CR287224DYHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	4/4/03	2.5	Yes	(64Mx4)*36	EOL
+ATP Electronics	AB28L72P4SMB0A	NT5DS64M4AT-7K	Nanya	SB184P04L1 rev 1	3/31/03	2.5	Yes	(64Mx4)*36	EOL
Infineon	HYS72D128021GR-7-B	HYB25D256400BT-7	Infineon		4/7/03	2.5		(64Mx4)*36	
+Avant Technology	AVM7228R82C5266K1-A	MT46V64M4TG-75 B rev B	Micron	50-1416-01-A rev A	4/17/03	2.5	Yes	(64Mx4)*36	EOL
+Smart Modular Technologies	SM12872RDDR301LP-N	17329-02	Nanya	P51G184NESZK002 rev A	4/17/03	2	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R38C2266K3-A	NT5DS64M4AT-7K rev A	Nanya	BRDB45A rev A	4/24/03	2		(64Mx4)*36	EOL

**Registered, ECC, DDR266 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Dataram	DTM63621F	HYB25D256400BT-7 rev B	Infineon	40556 rev B	4/30/03	2	Yes	(64Mx4)*36	
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	5/30/03	2	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R82C5266K 1-A	MT46V64M4TG-75 rev C	Micron	50-1416-01-A rev A	6/10/03	2.5	Yes	(64Mx4)*36	
+Legend	L1272YC5-PPBSDD5D	K4H560438D-TCB0 rev D	Samsung	18-21040B rev B	6/23/03	2.5	Yes	(64Mx4)*36	EOL
+Smart Modular Technologies	SM12872RDDR3H1L P-S	K4H510638D-TCB0 rev D	Samsung	M312L28 28T0	6/30/03	2.5	Yes	(64Mx4)*36	
ITAUCOM	01GE2665R24	MT46V64M4TG-75 rev C	Micron	0232 A	7/11/03	2.5	Yes	(64Mx4)*36	
Samsung	M312L2828ET0-CA2	K4H510638E-TCA2	Samsung		7/25/03	2	Yes	(64Mx4)*36	
+TRS	TRS21153	HYB25D256400BT-7 rev B	Infineon	M0531LA 1 rev 1	7/24/03	2	Yes	(64Mx4)*36	
+Viking	VI4CR287224DYHL3	MT46V64M4TG-75 rev C	Micron	03-0291 rev A	7/30/03	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7264R38C5266K 0-A	NT5DS64M4BT-75B rev B	Nanya	50-1415-01-B rev B	8/26/03	2.5	Yes	(64Mx4)*36	
+Ventura Technology Group	D54WPK28SV	K4H560438E-TCB0 rev E	Samsung	V213	9/18/03	2.5		(64Mx4)*36	
+Ventura Technology Group	D54WPK31SV	K4H560438E-TCB3	Samsung	V218	9/12/03	2.5	Yes	(64Mx4)*36	
Infineon	HYS72D128320GBR-7-B	HYB25D256400BC-7	Infineon		9/16/03	2	Yes	(64Mx4)*36	
Infineon	HYS72D128521GR-7-B	HYB25D256400BT-7	Infineon		10/1/03	2	Yes	(64Mx4)*36	
+Legend	L1272YC5-183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3	10/3/03	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R38C5266K 3-A	NT5DS64M4BT-75B rev B	Nanya	BRDB45A rev A	10/2/03	2.5		(64Mx4)*36	
Infineon	^HYS72D128320GBR-7F-B	HYB25D256400BC-7F	Infineon		10/7/03	2	Yes	(64Mx4)*36	
Micron	MT36VDDT12872G-265C2	MT46V64M4-75 C	Micron		10/10/03	2.5	Yes	(64Mx4)*36	
+ATP Electronics	AB28L72P4SMB0S	K4H560438E-TCB0 rev E	Samsung	SB184P0 4L1	11/6/03	2.5	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR301LP -I	HYB25D256400BT-7 rev B	Infineon	P54G184 NESZKR CN rev A	11/6/03	2	Yes	(64Mx4)*36	
Wintec Industries*	35952756L	HYB25D256400AT-7 rev A	Infineon	ZK2048M 84RBYJ	10/23/03	2.5	Yes	(64Mx4)*36	

**Registered, ECC, DDR266 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Avant Technology	AVM7228R82C5266K1-A	NT5DS64M4BT-75B rev B	Nanya	50-1416-01-A rev A	10/21/03	2.5	Yes	(64Mx4)*36	
+ATP Electronics	AB28L72U4SQB0S	K4H560438E-TCB0 rev E	Samsung	SB184U04L1	11/21/03	2.5		(64Mx4)*36	
+Legend	L1272YC5-RU1HDH5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818-A rev 1	12/09/03	2.5	Yes	(64Mx8)*18	
+Legacy Electronics Inc.	89L6MDLR-1LDG	LED128408TA-6	Legacy	LE36DDT1844R rev A	12/08/03	2.5	Yes	(128Mx4)*18	
+Smart Modular Technologies	SM12872RDDR301B G-I	HYB25D256400BC-6 rev B	Infineon	P54G184NESZBR CD rev A	12/22/03	2	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R53C5266K0-A	MT46V128M4TG-6T rev C	Micron	50-1415-01-B rev B	1/21/04	2.5	Yes	(128Mx4)*18	
+Centon Electronics	TOP02-D026Z	MT46V64M8TG-6T rev C	Micron	DR1G872-A	1/08/04	2.5	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872RDDR301H P-I	HYB25D256400BT-7 rev B	Infineon	P58G184NESZKG A1	2/5/04	2		(64Mx4)*36	
+TRS	TRS21174	HYB25D512800AT-7 rev A	Infineon	M0529LA1 rev 1	2/3/04	2	Yes	(64Mx8)*18	
+TRS	TRS21171	HYB25D256400BC-7 rev B	Infineon	M0533LA1 rev 1	2/11/04	2	Yes	(64Mx4)*36	
+Buffalo	DD266L-RW1G/SE	K4H560438E-TCB0 rev E	Samsung	4D248EF-AA	1/27/04	2.5	Yes	(64Mx4)*36	
Dataram	DTM63653H	HYB25D256400BC-6 rev B	Infineon	40599A rev A	3/15/04	2	Yes	(64Mx4)*36	
+Legacy Electronics Inc.	89L6JDGR-1LDG	LED64408TA-6 rev B	Legacy	LE36DDF1844RLP rev A	4/7/04	2.5	Yes	(64Mx4)*36	
+Ventura Technology Group	D54WYK25SV	K4H510838B-TCB3 rev B	Samsung	V208	3/19/04	2.5		(64Mx8)*18	
+Ventura Technology Group	D54WCK34SV	K4H560438E-GCB3 rev E	Samsung	V223	3/17/04	2.5	Yes	(64Mx4)*36	
+Legacy Electronics Inc.	89S6JDLC-1JDG	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	4/14/04	2	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR301B GAS	K4H560438E-GCB3 rev E	Samsung	P54G184NESZBR CD	4/14/04	2	Yes	(64Mx4)*36	

**Registered, ECC, DDR266 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Avant Technology	AVM7228R52C5266K1-A	MT46V64M8TG(P)-75 rev C	Micron	50-1411-01-A rev A	4/20/04	2.5	Yes	(64Mx8)*18	
+ATP Electronics	AB28L72Q8SHB0S	K4H510838B-TCB3 rev B	Samsung	SB184Q08L1 rev 1	5/6/04	2.5	Yes	(64Mx8)*18	
+Ventura Technology Group	D54WYK42SV	K4H510838B-TCB3 rev B	Samsung	DR1G872-A	5/27/04	2.5	Yes	(64Mx8)*18	
Kingston	KVR266X72RC25/1024	K4H510438B-TCB0 rev B	Samsung	2025127-001.A00	6/4/04	2.5	Yes	(128Mx4)*18	
+Dataram	DTM63698B	HYB25D512400BE-7 rev B	Infineon	40581A rev A	7/16/04	2	Yes	(128Mx4)*18	
+Viking	VI4CR287228ETHL2	MT46V64M8TG(P)-6T rev C	Micron	0000985A	7/7/04	2.5	Yes	(64Mx8)*18	
+Wintec Industries	3C953641-L	HYB25D256400BC-6 rev B	Infineon	ZK4096M84RCJB	8/5/04	2.5	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR301B GIC	HYB25D256400CC-6 rev C	Infineon	P54G184 NESZBR CD	8/2/04	2	Yes	(64Mx4)*36	
+Wintec Industries	3C952681-L	HYB25D512800BE-5 rev B	Infineon	85616649	8/13/04	2.5	Yes	(64Mx8)*18	
+Smart Modular Technologies	SX12872RDDR308BT IB	HYB25D512800BE-6 rev B	Infineon	P52G184 NEBZ6RC L rev B	10/5/04	2	Yes	(64Mx8)*18	
+TRS	TRS21203	HYB25D512400BE-7 rev B	Infineon	M0530LA1 rev 1	11/4/04	2	Yes	(128Mx4)*18	
Samsung	M383L2828ET1-CB0	K4H510638E-TCB0	Samsung		11/2/04	2.5		(64Mx4)*18	
Samsung	M312L2828ET0-CAA	K4H510638E-TCAA	Samsung		11/2/04	2	Yes	(64Mx4)*36	
Micron	MT36VDDT12872G-262C3	MT46V64M4FG-75E	Micron		11/2/04	2	Yes	(64Mx4)*36	
Micron	MT36VDDF12872G-265C3	3RC11-D9BHV	Micron		11/2/04	2.5	Yes	(64Mx4)*36	
Kingston	KVR266D4R25/1GI	HYB25D256400BT-7 rev B	Infineon	2025148-001.A00	3/7/05	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R52C5266K1-MTD	MT46V64M8TG-6T rev D	Micron	50-1411-01-A rev A	6/16/05	2.5	Yes	(64Mx8)*18	

**Registered, ECC, DDR333 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333L-R1G/SB	K4H510838B-TCB3 rev B	Samsung	1D188EF-AA	9/2/04	2.5	Yes	(64Mx8)*18	
+Viking	VI4CR287224DBKL2	K4H560438E-GCB3 rev E	Samsung	0000972B	10/13/04	2.5	Yes	(64Mx4)*36	
+TRS	TRS21197	HYB25D256400CC-6 rev C	Infineon	M0533LA 1 rev 1	11/9/04	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R38C5333K 3-A	MT46V64M4TG(P)-6T rev C	Micron	BRDB45A rev A	11/3/04	2.5		(64Mx4)*36	
+Avant Technology	AVM7228R52C5333K 1-MTD	MT46V64M8TG(P)-6T rev D	Micron	50-1411-01-A rev A	11/24/04	2.5	Yes	(64Mx8)*18	
+Buffalo	DD333L-R1G/MD	MT46V64M8TG(P)-6T rev D	Micron	1D188EF-AA	12/15/04	2.5	Yes	(64Mx8)*18	
+Avant Technology	AVM7228R52C5333K 1MTDP	MT46V64M8P-6T rev D	Micron	50-1411-01-A rev A	3/25/05	2.5	Yes	(64Mx8)*18	
+Kingston	KVR333D4R25/1GI	HYB25D256400CC-6 rev C	Infineon	2025247-001.A00	6/20/05	2.5	Yes	(64Mx4)*36	
+Kingston	KVR333D4R25/1GI	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na	7/15/05	2.5	Yes	(64Mx4)*36	
+Legend	L1272YC6-PPXSDD2E	K4H560438E-GCB3 rev E	Samsung	DR2G472 B na	12/7/05	2.5	Yes	(64Mx4)*36	
+Legend	L1272YC6-PPXSDM1B	K4H510438B-GCB3 rev B	Samsung	M312L64 20G0 na	12/12/05	2.5	Yes	(128Mx4)*18	

**Modules shaded in blue are low profile.**

**Modules in bold text do not contain Lead.**

(^)This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal and physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

**Note:** Some modules on this list may contain "stacked" DRAM parts. Stacked (low profile) 1GB DIMMs and all 2GB DIMM parts require a special memory-cooling duct be installed on the SE7505VB2 server board. Please consult the Intel Server Board SE7505VB2 Technical Product Specification for details on obtaining and using this duct

## Server Board SE7505VB2

### Registered, ECC, DDR266 DIMM Modules 2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L5628MT0-CB0	K4H1G0638M-TCB0	Samsung		12/22/02	2.5	Yes	(128Mx4)* 36	
Infineon	HYS72D256520GR-7-A	HYB25D512400A T-7	Infineon		2/11/03	2	Yes	(128Mx4)* 36	
+ATP Electronics	AB56L72P4SMB0S	K4H510438M-TCB0	Samsung	SB184P0 4L1	3/12/03	2.5	Yes	(128Mx4)* 36	EOL
+Viking	VI4CR567224EYHL2	K4H510438M-TCA2	Samsung	03-0291 rev A	4/11/03	2.5	Yes	(128Mx4)* 36	EOL
+Smart Modular Technologies	SM25672RDDR301LP-I	HYB25D512400A T-7 rev A	Infineon	P54G184 NESZKR CN rev A	6/3/03	2	Yes	(128Mx4)* 36	
+TRS	TRS21155	HYB25D512400A T-7 rev A	Infineon	M0531LA 1 rev 1	9/2/03	2	Yes	(128Mx4)* 36	
Infineon	◇HYS72D256520GR-7F-A	HYB25D512400A T-7F	Infineon		9/26/03	2	Yes	(128Mx4)* 36	
+Avant Technology	AVM7256R83C5266K1-A	MT46V128M4TG-75 rev C	Micron	50-1416-01-A rev A	10/9/03	2.5	Yes	(128Mx4)* 36	
+Dataram	DTM63663B	HYB25D512400A T-7 rev A	Infineon	40556 rev B	10/17/03	2	Yes	(128Mx4)* 36	
+Smart Modular Technologies	SM25672RDDR301HP-I	HYB25D512400A T-7 rev A	Infineon	P52G184 NESZKG A1	11/11/03	2		(128Mx4)* 36	
+Legacy Electronics Inc.	8AL6MDLC-1LDG	LED128408TA-6	Legacy	LE36DDT 1844R rev A	12/12/03	2.5	Yes	(128Mx4)* 36	
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213	4/7/04	2.5		(128Mx4)* 36	
+Legacy Electronics Inc.	8AS6MDLC-1JDG	HYB25D512400A T-7 rev A	Infineon	LE36DDT 1844R	4/12/04	2	Yes	(128Mx4)* 36	
Kingston	KVR266X72RC25/2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00	7/2/04	2.5	Yes	(128Mx4)* 36	
+TRS	TRS21218	HYB25D512400B E-7 rev B	Infineon	M0531LA 1 rev 1	7/25/05	2	Yes	(128Mx4)* 36	

**Registered, ECC, DDR333 DIMM Modules  
2GB Sizes (256Mx72)**

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>EOL</b>
+Legend	L2572YC6-PPXSDM5B	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B	3/16/05	2.5	Yes	(128Mx4)* 36	
+Kingston	KVR333D4R25/2GI	HYB25D512400B C-6 rev B	Infineon	2025294-001.A00	4/12/05	2.5	Yes	(128Mx4)* 36	
+Kingston	KVR333D4R25/2GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na	10/6/05	2.5	Yes	(128Mx4)* 36	
+Legend	L2572YC6-PPXSMDMB	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B (0403)	12/15/05	2.5	Yes	(128Mx4)* 36	

*Modules shaded in blue are low profile.*

**Modules in bold text do not contain Lead.**

(^)This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain “stacked” DRAM parts. These parts may have thermal and physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support “stacked” parts before purchase.

**Note:** Some modules on this list may contain “stacked” DRAM parts. Stacked (low profile) 1GB DIMMs and all 2GB DIMM parts require a special memory cooling duct be installed on the SE7505VB2 server board. Please consult the Intel Server Board SE7505VB2 Technical Product Specification for details on obtaining and using this duct

## Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	<a href="http://www.atpusa.com/">http://www.atpusa.com/</a>	Florence Hsieh Tel 408-732-5831 Fax 408-732-5055 <a href="mailto:sales@atpusa.com">sales@atpusa.com</a>
ATP Electronics -- Taiwan Inc.	<a href="http://www.atpusa.com/">http://www.atpusa.com/</a>	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	<a href="http://www.avanttechnology.com">http://www.avanttechnology.com</a>	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 <a href="mailto:brads@avanttechnology.com">brads@avanttechnology.com</a>
Aved Memory Products	<a href="http://www.avedmemory.com/">http://www.avedmemory.com/</a>	
Buffalo Technology	<a href="http://www.buffalotech.com/">http://www.buffalotech.com/</a>	(800) 967-0959 <a href="mailto:memory@buffalotech.com">memory@buffalotech.com</a>
Centon Electronics	<a href="http://www.centon.com">http://www.centon.com</a>	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	<a href="http://www.corsairmicro.com/">http://www.corsairmicro.com/</a>	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	<a href="http://www.dane-memory.com/">http://www.dane-memory.com/</a>	Michal Hassan @ (949)450-2941 or email @ <a href="mailto:Michal@Dane-memory.com">Michal@Dane-memory.com</a>
Dataram	<a href="http://www.dataram.com/">http://www.dataram.com/</a>	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 <a href="mailto:phenke@dataram.com">phenke@dataram.com</a>
GoldenRAM	<a href="http://www.goldenram.com">http://www.goldenram.com</a>	Jason M. Barrette @ 800-222-861 x7546 <a href="mailto:jasonb@goldenram.com">jasonb@goldenram.com</a> or Michael E. Meyer @800-222-8861 x7512 <a href="mailto:michaelm@goldenram.com">michaelm@goldenram.com</a>
Hitachi	<a href="http://semiconductor.hitachi.com/pointer/">http://semiconductor.hitachi.com/pointer/</a>	
Hyundai/Hynix Semiconductor	<a href="http://www.heacom.com/">http://www.heacom.com/</a>	
Infineon	<a href="http://www.infineon.com/business/distribut/index.htm">http://www.infineon.com/business/distribut/index.htm</a>	
ITAUCOM	<a href="http://www.itauc.com.br">http://www.itauc.com.br</a>	
JITCO CO LTD	<a href="http://www.jitco.net/">http://www.jitco.net/</a>	Seong Jeon Tel: 82-32-817-9740 <a href="mailto:s.jeon@jitco.net">s.jeon@jitco.net</a>
Kingston	<a href="http://www.kingston.com">http://www.kingston.com</a>	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	<a href="http://www.legacyelectronics.com">http://www.legacyelectronics.com</a>	U.S. Contact: Keri Albers 888 466 3853 ext. 307 European Contact: 49 89 370 664 11
Legend	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	
Micron	<a href="http://silicon.micron.com/mktg/">http://silicon.micron.com/mktg/</a> <a href="http://silicon.micron.com/mktg/mbqual/qual_data.cfm">http://silicon.micron.com/mktg/mbqual/qual_data.cfm</a>	
MSC Vertriebs GmbH	<a href="http://www.msc-ge.com">http://www.msc-ge.com</a>	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 <a href="mailto:wpe@msc-ge.com">wpe@msc-ge.com</a>



<b>Vendor Name</b>	<b>Web URL</b>	<b>Vendor Direct Sales Info</b>
<b>Netlist, Inc</b>	<a href="http://www.netlistinc.com">http://www.netlistinc.com</a>	Christopher Lopes 949.435.0025 tel 949.435.0031 fax <a href="mailto:sales@netlistinc.com">sales@netlistinc.com</a>
<b>Peripheral Enhancements</b>	<a href="http://www.peripheral.com/">http://www.peripheral.com/</a>	
<b>Samsung</b>	<a href="http://www.korea.samsungsemi.com/locate/buy/list_na.html">http://www.korea.samsungsemi.com/locate/buy/list_na.html</a>	For US customers go to: <a href="http://www.mymemorystore.com/">http://www.mymemorystore.com/</a>
<b>Silicon Tech</b>	<a href="http://www.silicontech.com/contact/salescontacts.shtml">http://www.silicontech.com/contact/salescontacts.shtml</a>	
<b>Simple Tech</b>	<a href="http://www.simpletech.com">http://www.simpletech.com</a>	Ron Darwish @ (949) 260-8230 or email @ <a href="mailto:Rdarwish@Simpletech.com">Rdarwish@Simpletech.com</a>
<b>SMART Modular Technologies</b>	<a href="http://www.smartm.com/channel">http://www.smartm.com/channel</a>	Gene Patino (949) 439-6167 <a href="mailto:Gene.Patino@Smartm.com">Gene.Patino@Smartm.com</a>
<b>Swissbit</b>	<a href="http://www.swissbit.com">http://www.swissbit.com</a>	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 <a href="mailto:tony.cerreta@swissbitna.com">tony.cerreta@swissbitna.com</a>
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<b>TRS* Tele-Radio-Space GmbH</b>	<a href="http://www.certified-memory.com">http://www.certified-memory.com</a> <a href="http://www.certified-memory.de">http://www.certified-memory.de</a>	Vendor Direct Sales Info: Andreas Gründl, Pho.: +49(0)89/94553234, Fax.: +49(0)89/94553293, <a href="mailto:agruendl@trs-space.de">agruendl@trs-space.de</a>
<b>Unigen</b>	<a href="http://www.unigen.com">http://www.unigen.com</a>	
<b>Ventura Technology Inc</b>	<a href="http://www.venturatech.com">http://www.venturatech.com</a>	Don Hummel @ 805-581-0800 x 108 or email @ <a href="mailto:don@venturatech.com">don@venturatech.com</a>
<b>Viking InterWorks</b>	<a href="http://www.vikinginterworks.com">http://www.vikinginterworks.com</a>	
<b>Virtium Technology Inc</b>	<a href="http://www.virtium.com">http://www.virtium.com</a>	Tod Skelton @ (949) 460-0020 ext. 146 or email @ <a href="mailto:tod.skelton@virtium.com">tod.skelton@virtium.com</a>
<b>Legend</b>	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	Tel: 800-338-2361 Fax: 949-459-8577 <a href="mailto:orderdesk@vikingcomponents.com">orderdesk@vikingcomponents.com</a>
<b>Wintec Industries</b>	<a href="http://www.wintecindustries.com">http://www.wintecindustries.com</a>	Tel 510-360-6300 Fax 510-770-9338

### **CMTL\* (Computer Memory Test Labs)**

CMTL\* is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

#### **IMPORTANT NOTE**

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar device type or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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